

BL100

Table Top Die Bonder



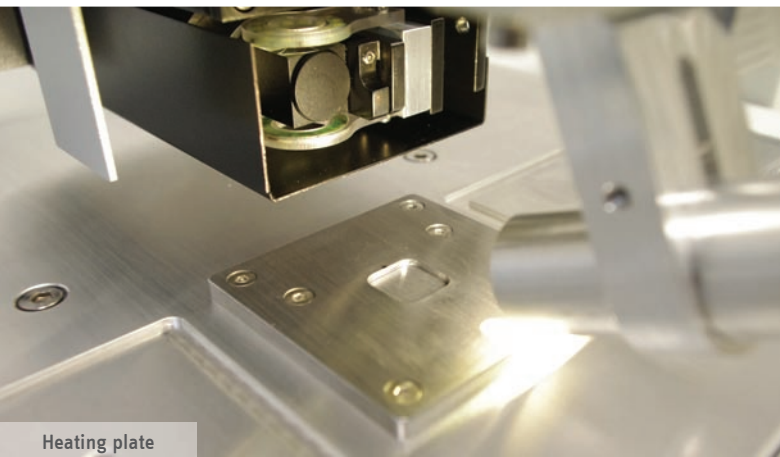
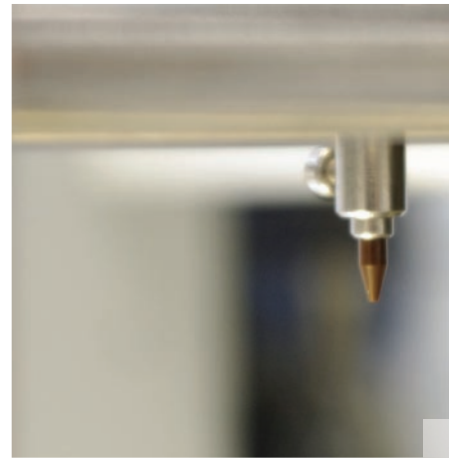
ficonTEC
micro assembly machines

BL100 Table Top Die Bonder

BL100 is the entry level die bonder from ficonTEC's BL series of eutectic die bonders. Be it for lower volume production or for R&D purposes this table-top semi-automatic pick & place die bonder offers quick results yet with exceptional placement accuracy.

Fields of Usage

- Eutectic die bonding
- Epoxy die bonding
- Chip sorting
- CoS (Chip on Submount)
- MEMS/MOEMS assembly
- Sensors assembly
- Assembly of optical components (photo diodes, laser diodes)
- Assembly of mechanical components
- Applications in the field of medical technology



Heating plate

Features

- Semi automatic manual die bonder
- Programmable motorized Z-stage
- Fine adjustment of X- and Y-stages

- Placement accuracy: +/- 5 microns
- Working area: 300 x 300 mm
- Component length (max): 10 mm
- Substrate size (max): 25 x 25 mm

Simple Solutions for best Results

The BL100 is a versatile handling system designed for micro assembly applications like die bonding or component handling.

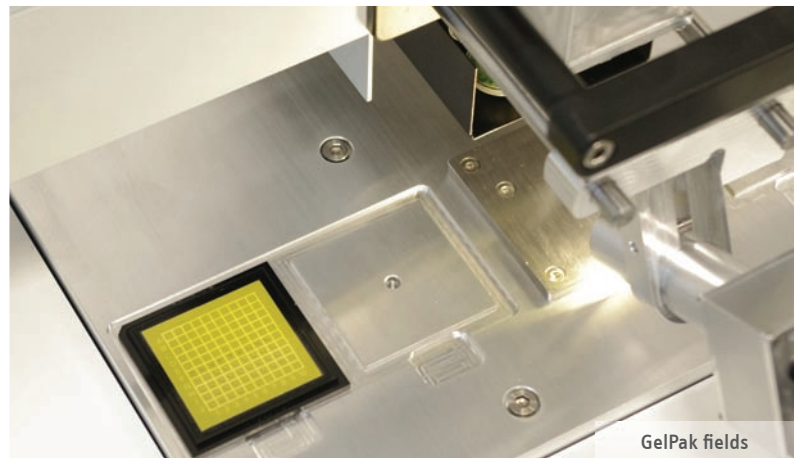
The BL100 is an assembling platform utilizing an overhead gantry arrangement with an integrated imaging system. This arrangement provides a maximum working area at minimal installation area.

Available Modules

- Dispenser module
- Heating plates
- Heated pick-up tools
- Support plate with vacuum
- Height adjustable bond plate
- High force module
- Observation camera



Vacuum component gripper



GelPak fields

Intuitive Operation

With the integrated dual imaging optics in combination with the programmable Z-stage this system is well suited for simple sorting or assembly applications as well as for reproducible bonding of electronic and opto-electronic components.

A physically generated overlay live image allows the operator to intuitively perform the component alignment.

Available options such as different heating plates, heated placement tools, or dispenser further extend the usability of the system.

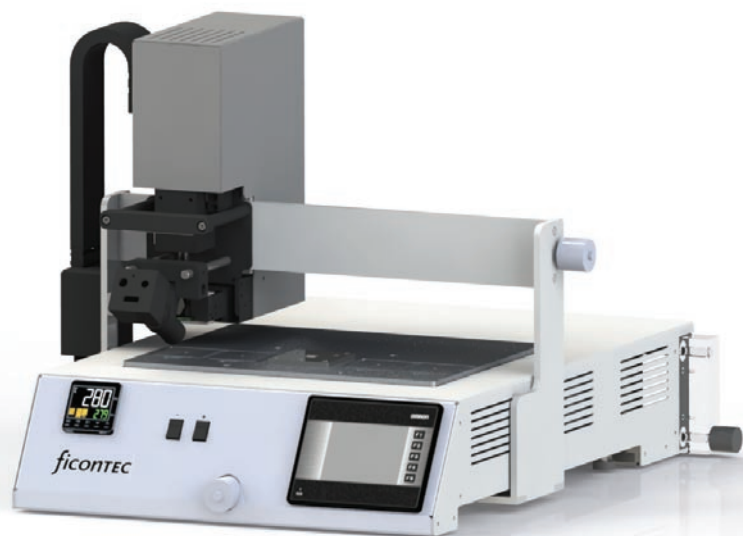


Table Top System, BL100

ficontec

What we do

ficonTEC designs and produces high precision production equipment for the assembling or testing of components.

We are the market leader when it comes to automated assembly or test of micro-optics or opto-electronics such as laser diode manufacture, medical technology, security and defense engineering, as well as telecommunication.



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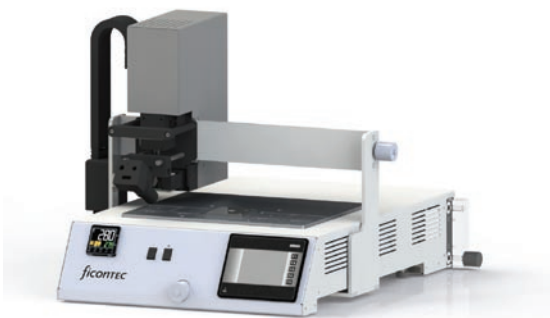
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ISO 9001 Certification

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